

What is claimed is:

1. A semiconductor wafer having circuits formed on the front surface of a base plate, wherein an ID mark is formed in the interior of the base plate at a predetermined position  
5 devoid of the circuits.
2. The semiconductor wafer according to claim 1, wherein the ID mark is formed by converging a laser beam at a focal point in the interior of the base plate.  
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3. A substrate having a workpiece holding area in a base plate, wherein an ID mark is formed in the interior of the base plate at a predetermined position.
- 15 4. The semiconductor wafer according to claim 3, wherein the ID mark is formed by converging a laser beam at a focal point in the interior of the base plate.